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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A module substrate mounting structure comprising:

a motherboard having connecting pads disposed on a surface thereof; and

a plurality of module substrates each having connecting members attached to a surface thereof via connecting terminals disposed on each of said plurality of module substrates; wherein

said plurality of module substrates are stacked with a space therebetween on said motherboard, said connecting members of said plurality of module substrates are electrically connected to said connecting pads on said motherboard, a plurality of said connecting members are arranged along an edge portion of each of said plurality of module substrates, said plurality of module substrates are stacked with said connecting members aligned with each other, a plurality of said connecting pads are arranged on the surface of said motherboard in the direction of arrangement of said connecting members, a plurality of rows of said connecting pads are arranged to be sequentially offset from one another from an inner region of said motherboard where said module substrates are mounted toward an outer region of said ~~mother-substrate~~motherboard, said connecting members of an upper module substrate of said plurality of module substrates are electrically connected to an outer row of connecting pads and said connecting members of a lower module substrate are electrically connected to an inner row of connecting pads disposed inwardly of said outer row of connecting pads, the length of said connecting members increases as the position of respective ones of said plurality of module substrates connected thereto is higher, and said connecting

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members connected to said upper module substrate project further from said upper module substrate than said connecting members connected to said lower module substrate.

Claim 2 (previously presented): A module substrate mounting structure according to Claim 1, wherein said plurality of module substrates have a nozzle suction area that is arranged to be drawn by a component-transporting suction nozzle.

Claim 3 (previously presented): A module substrate mounting structure according to Claim 1, wherein a ratio of a length to a width of each of said plurality of module substrates is within a range of about 1/3 to about 1/1.

Claim 4 (previously presented): A module substrate mounting structure according to Claim 1, wherein said plurality of module substrates have a converter power-supply circuit.

Claim 5 (currently amended): A module substrate mounting structure comprising:

a motherboard having connecting pads disposed on a surface thereof; and

a plurality of module substrates each having connecting members attached to a surface thereof via connecting terminals disposed on each of said plurality of module substrates; wherein

said plurality of module substrates are stacked with a space therebetween on said motherboard, said connecting members of said plurality of module substrates are electrically connected to said connecting pads on said motherboard, a plurality of said connecting terminals are arranged along an edge portion of each of said plurality of module substrates, said plurality of module substrates are stacked ~~on~~ in a direction perpendicular to a surface of said motherboard and are sequentially offset from one

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another in the direction of ~~arrangement of said connecting terminals~~ parallel to the surface of said motherboard, ~~so that~~ said edge portions with said connecting terminals disposed thereon are aligned with one another in ~~a stacking~~ the direction perpendicular to a surface of said motherboard, and said connecting pads ~~electrically~~ connected to said connecting terminals arranged along the edge portion of each of said plurality of module substrates via said connecting members are arranged in the same row.

Claim 6 (previously presented): A module substrate mounting structure according to Claim 5, wherein a lower substrate recognition mark is located on an exposed portion of a lower module substrate of said plurality of module substrates.

Claim 7 (previously presented): A module substrate mounting structure according to Claim 5, wherein said plurality of module substrates have a nozzle suction area that is arranged to be drawn by a component-transporting suction nozzle.

Claim 8 (previously presented): A module substrate mounting structure according to Claim 5, wherein a ratio of a length to a width of each of said plurality of module substrates is within a range of about 1/3 to about 1/1.

Claim 9 (previously presented): A module substrate mounting structure according to Claim 5, wherein said plurality of module substrates have a converter power-supply circuit.

Claim 10 (previously presented): A module substrate mounting structure comprising:

a motherboard having connecting pads disposed on a surface thereof; and
a plurality of module substrates each having connecting members attached to a surface thereof via connecting terminals disposed on each of said plurality of module

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substrates; wherein

said plurality of module substrates are stacked with a space therebetween on said motherboard, said connecting members of said plurality of module substrates are electrically connected to said connecting pads on said motherboard, a plurality of said connecting terminals are arranged along an edge portion of each of said plurality of module substrates, said plurality of module substrates are stacked on said motherboard and are sequentially offset from one another in the direction of arrangement of said connecting terminals so that said edge portions with said connecting terminals disposed thereon are aligned with one another in a stacking direction, a plurality of said connecting pads are arranged on the surface of said motherboard in the direction of arrangement of said connecting terminals, a plurality of rows of said connecting pads are arranged to be sequentially offset from one another from an inner region on said motherboard where said plurality of module substrates are mounted toward an outer region of said motherboard, said connecting members of an upper module substrate of said module substrates are electrically connected to an outer row of said plurality of rows of connecting pads and said connecting members of a lower module substrate are electrically connected to an inner row of connecting pads disposed inwardly of said outer row of connecting pads, and said connecting members connected to said upper module substrate project further from said upper module substrate than said connecting members connected to said lower module substrate.

Claim 11 (previously presented): A module substrate mounting structure according to Claim 10, wherein a lower substrate recognition mark is located on an exposed portion of said lower module substrate.

Claim 12 (previously presented): A module substrate mounting structure according to Claim 10, wherein said plurality of module substrates have a nozzle suction area that is arranged to be drawn by a component-transporting suction nozzle.

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Claim 13 (previously presented): A module substrate mounting structure according to Claim 10, wherein a ratio of a length to a width of each of said plurality of module substrates is within a range of about 1/3 to about 1/1.

Claim 14 (previously presented): A module substrate mounting structure according to Claim 10, wherein said plurality of module substrates have a converter power-supply circuit.

Claim 15 (currently amended): A module substrate mounting structure comprising:

a motherboard having connecting pads disposed on a surface thereof; and

a plurality of module substrates each having connecting members attached to a surface thereof via connecting terminals disposed on each of said plurality of module substrates; wherein

said plurality of module substrates are stacked with a space therebetween on said motherboard, said connecting members of said plurality of module substrates are electrically connected to said connecting pads on said motherboard, a plurality of said connecting terminals are arranged along a pair of edge portions of each of said plurality of module substrates, and said module substrates are stacked with the space therebetween on said motherboard so that the direction of arrangement of said connecting terminals of an upper module substrate of said plurality of module substrates is substantially perpendicular to the direction of arrangement of said connecting terminals of a lower module substrate of said plurality of module substrates.

Claim 16 (previously presented): A module substrate mounting structure according to Claim 15, wherein said plurality of module substrates have a nozzle suction area that is arranged to be drawn by a component-transporting suction nozzle.

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Claim 17 (previously presented): A module substrate mounting structure according to Claim 15, wherein a ratio of a length to a width of each of said plurality of module substrates is within a range of about 1/3 to about 1/1.

Claim 18 (previously presented): A module substrate mounting structure according to Claim 15, wherein said plurality of module substrates have a converter power-supply circuit.